

CY7C164 CY7C166

# 16K x 4 Static RAM

#### Features

- High speed
  - 15 ns
- Output enable (OE) feature (CY7C166)
- CMOS for optimum speed/power
- · Low active power
  - 633 mW
- · Low standby power

Logic Block Diagram

- 110 mW
- TTL-compatible inputs and outputs
- Automatic power-down when deselected
- CY7C164 is available in non Pb-free 22-pin (300-Mil) Molded DIP, CY7C166 in non Pb-free 24-pin Molded SOJ

## **Functional Description**

The CY7C164 and CY7C166 are high-performance CMOS static RAMs organized as 16,384 by 4 bits. Easy memory expansion is provided by an active LOW Chip Enable ( $\overline{CE}$ ) and tri-state drivers. The CY7C166 has an active LOW Output Enable ( $\overline{OE}$ ) feature. Both devices have an automatic powerdown feature, reducing the power consumption by 65% when deselected.

<u>Rea</u>ding the device is accomplished by taking Chip Enable  $(\overline{CE})$  LOW (and  $\overline{OE}$  LOW for CY7C166), while Write Enable (WE) remains HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the four data I/O pins.

<u>The</u> I/O pins stay in a high-impedance state when Chip Enable ( $\overline{CE}$ ) is HIGH (or Output Enable ( $\overline{OE}$ ) is HIGH for CY7C166). A die coat is used to insure alpha immunity.

#### INPUT BUFFER Д I/O<sub>3</sub> DECODEF AMPS $I/O_2$ 16K x 4 SENSE , ARRAY $I/O_1$ NO $I/O_0$ ናጉ POWEF DOWN COLUMN CE DECODER A11 A<sub>13</sub>→ A<sub>12</sub>J WE ÅÅ Å (OE) (7C166 ONLY)

## **Pin Configurations**

	DIP Top Vie	w	_		Т	SOJ op View
A <sub>5</sub> A <sub>6</sub> A <sub>7</sub> A <sub>8</sub> A <sub>10</sub> A <sub>10</sub> A <sub>11</sub> A <sub>12</sub> A <sub>12</sub> A <sub>13</sub> CE	1 2 3 4 5 6 7C164 7 8	22 21 20 19 18	□ Vcc □ A <sub>4</sub> □ A <sub>3</sub> □ A <sub>2</sub> □ A <sub>1</sub> □ A <sub>0</sub> □ I/O <sub>3</sub> □ I/O <sub>2</sub> □ I/O <sub>1</sub> □ I/O <sub>1</sub>	A5 A6 A7 A9 A9 A10 A11 A12 A12 A13 CE	1 2 3 4 5 6 7 8	24 Vcc 23 A <sub>4</sub> 22 A <sub>3</sub> 21 A <sub>2</sub> 20 A <sub>1</sub> 7C166 19 A <sub>0</sub> 18 NC 17 I/O <sub>3</sub> 16 I/O <sub>2</sub> 15 I/O <sub>1</sub>
GND 🗌	11	12	WE	OE GND	11 12	14 ☐ I/O <sub>0</sub> 13 ☐ WE

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## **Selection Guide**

	CY7C164-15 CY7C166-15	CY7C164-25 CY7C166-25
Maximum Access Time (ns)	15	25
Maximum Operating Current (mA)	115	105
Maximum CMOS Standby Current (mA)	20	20

## **Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage to Ground Potential0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State <sup>[1]</sup> –0.5V to +7.0V
DC Input Voltage <sup>[1]</sup> 0.5V to +7.0V

Output Current into Outputs (LOW)	20 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	>200 mA

#### **Operating Range**

Range	Ambient Temperature	v <sub>cc</sub>
Commercial	0°C to +70°C	$5V\pm10\%$

#### Electrical Characteristics Over the Operating Range

			–15			25	
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC}$ = Min., $I_{OH}$ = -4.0 mA	2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Leakage Current	$GND \leq V_I \leq V_{CC}$	-5	+5	-5	+5	μA
I <sub>OZ</sub>	Output Leakage Current	$GND \leq V_O \leq V_{CC}$ , Output Disabled	-5	+5	-5	+5	μA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	$V_{CC} = Max., I_{OUT} = 0 mA$		115		105	mA
I <sub>SB1</sub>	Automatic CE Power-Down Current <sup>[2]</sup>	Max. $V_{CC}$ , $\overline{CE} \ge V_{H}$ , Min. Duty Cycle = 100%		40		20	mA
I <sub>SB2</sub>	Automatic CE Power-Down Current <sup>[2]</sup>	$\begin{array}{l} \text{Max. } V_{\text{CC}}, \overline{\text{CE}} \geq V_{\text{CC}} - 0.3\text{V}, \\ V_{\text{IN}} \geq V_{\text{CC}} - 0.3\text{V} \text{ or } V_{\text{IN}} \leq 0.3\text{V} \end{array}$		20		20	mA

#### Capacitance<sup>[3]</sup>

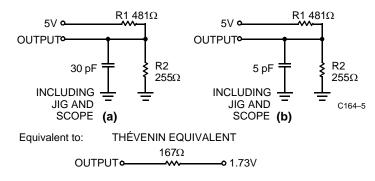
Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	10	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.0V$	10	pF

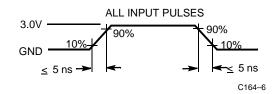
Notes:

Minimum voltage is equal to -3.0V for pulse durations less than 30 ns.
 A pull-up resistor to V<sub>CC</sub> on the CE input is required to keep the device deselected during V<sub>CC</sub> power-up, otherwise I<sub>SB</sub> will exceed values given.
 Tested initially and after any design or process changes that may affect these parameters.



## **AC Test Loads and Waveforms**





## Switching Characteristics Over the Operating Range<sup>[4]</sup>

				164-15 166-15		164-25 166-25	
Parameter	Description		Min.	Max.	Min.	Max.	Unit
READ CYCLE							
t <sub>RC</sub>	Read Cycle Time		15		25		ns
t <sub>AA</sub>	Address to Data Valid			15		25	ns
t <sub>OHA</sub>	Output Hold from Address Change		3		5		ns
t <sub>ACE</sub>	CE LOW to Data Valid			15		25	ns
t <sub>DOE</sub>	OE LOW to Data Valid	7C166		10		12	ns
t <sub>LZOE</sub>	OE LOW to Low Z	7C166	3		3		ns
t <sub>HZOE</sub>	OE HIGH to High Z	7C166		8		10	ns
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[5]</sup>		3		5		ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[5, 6]</sup>			8		10	ns
t <sub>PU</sub>	CE LOW to Power-Up		0		0		ns
t <sub>PD</sub>	CE HIGH to Power-Down		15		20	ns	
WRITE CYCLE <sup>[7</sup>	7]						
t <sub>WC</sub>	Write Cycle Time		15		20		ns
t <sub>SCE</sub>	CE LOW to Write End		12		20		ns
t <sub>AW</sub>	Address Set-Up to Write End		12		20		ns
t <sub>HA</sub>	Address Hold from Write End		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start		0		0		ns
t <sub>PWE</sub>	WE Pulse Width		12		15		ns
t <sub>SD</sub>	Data Set-Up to Write End		10		10		ns
t <sub>HD</sub>	Data Hold from Write End		0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[5]</sup>		5		5		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[5, 6]</sup>			7		7	ns

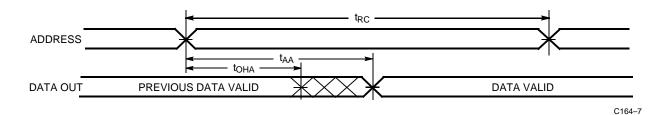
Notes:

Notes:
4. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified lo<sub>L</sub>/l<sub>OH</sub> and 30-pF load capacitance.
5. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> for any given device. These parameters are guaranteed by design and not 100% tested.
6. t<sub>HZCE</sub> and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) in AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
7. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

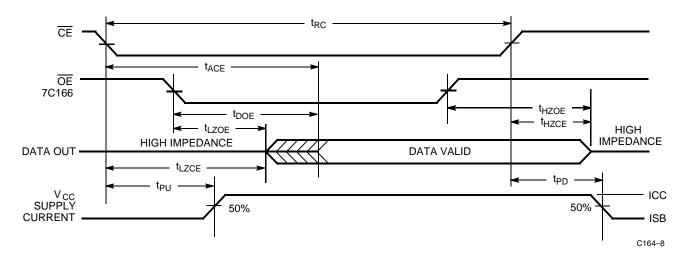


## **Switching Waveforms**

Read Cycle No. 1<sup>[8,9]</sup>



## Read Cycle No. 2<sup>[8,10]</sup>



- Notes:

   8. WE is HIGH for read cycle.

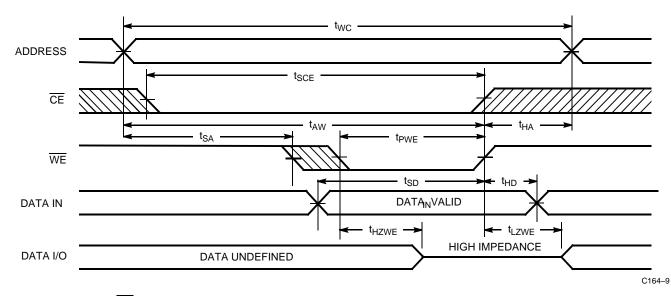
   9. Device is continuously selected,  $\overline{CE} = V_{|L-}(CY7C166; \overline{OE} = V_{|L} also).$  

   10. Address valid prior to or coincident with CE transition LOW.

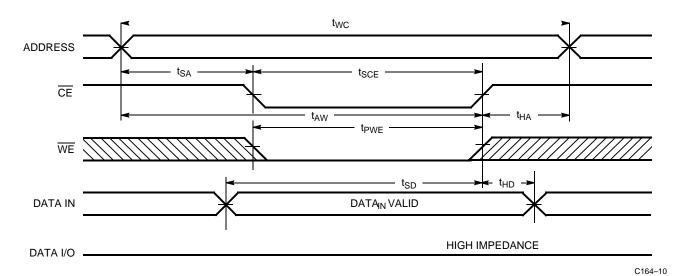


#### Switching Waveforms (continued)

Write Cycle No. 1(WE Controlled)<sup>[7,11]</sup>



Write Cycle No. 2(CE Controlled)<sup>[7,11,12]</sup>

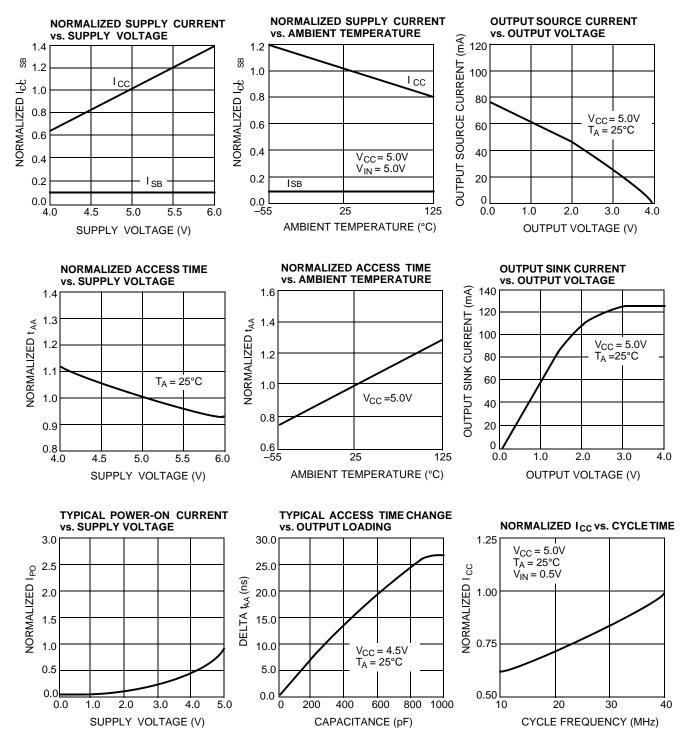


Notes:

11. CYTC166 only: Data I/O will be high-impedance if  $\overline{OE} = V_{IH}$ . 12. If  $\overline{CE}$  goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.



## **Typical DC and AC Characteristics**





## CY7C164 Truth Table

CE	WE	Input/Output	Mode	Power
Н	Х	High Z	Deselect/Power-Down	Standby (I <sub>SB</sub> )
L	Н	Data Out	Read	Active (I <sub>CC</sub> )
L	L	Data In	Write	Active (I <sub>CC</sub> )

#### CY7C166 Truth Table

CE	WE	OE	Input/Output	Mode	Power
Н	Х	Х	High Z	Deselect/Power-Down	Standby (I <sub>SB</sub> )
L	Н	L	Data Out	Read	Active (I <sub>CC</sub> )
L	L	Н	Data In	Write	Active (I <sub>CC</sub> )
L	Н	Н	High Z	Select/Output Disabled	Active (I <sub>CC</sub> )

## **Address Designators**

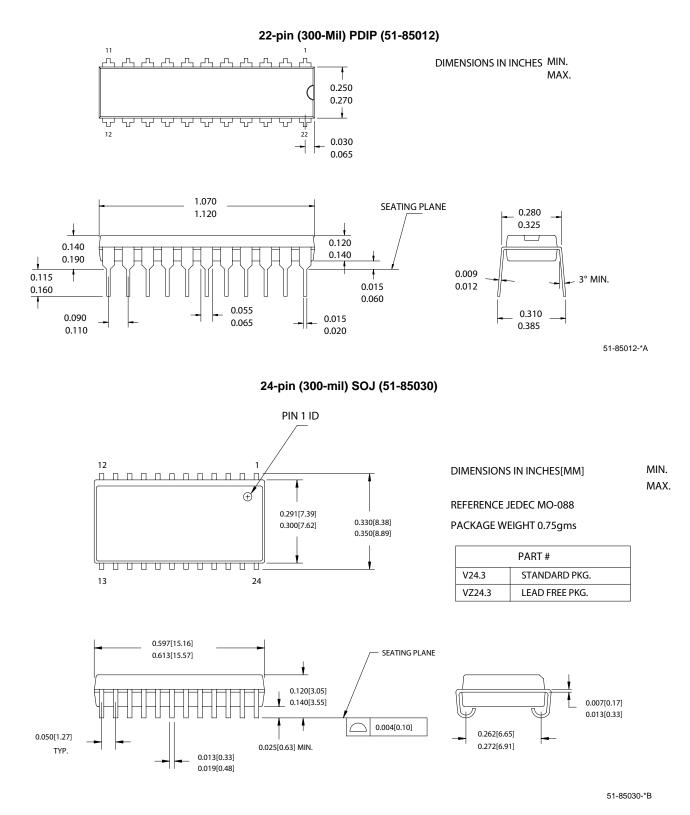
Address Name	Address Function	CY 7C164 Pin Number	CY7C166 Pin Number
A5	X3	1	1
A6	X4	2	2
A7	X5	3	3
A8	X6	4	4
A9	X7	5	5
A10	Y5	6	6
A11	Y4	7	7
A12	Y0	8	8
A13	Y1	9	9
A0	Y2	17	19
A1	Y3	18	20
A2	X0	19	21
A3	X1	20	22
A4	X2	21	23

## **Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C164-15PC	51-85012	22-pin (300-Mil) Molded DIP	Commercial
	CY7C166-15VC	51-85030	24-pin (300-Mil) Molded SOJ	
25	CY7C164-25PC	51-85012	22-pin (300-Mil) Molded DIP	Commercial
	CY7C166-25VC	51-85030	24-pin (300-Mil) Molded SOJ	



## Package Diagrams



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## **Document History Page**

Document Title: CY7C164/CY7C166 16K x 4 Static RAM Document Number: 38-05025				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	106811	09/10/01	SZV	Change from Spec number: 38-00032 to 38-05025
*A	486744	See ECN	NXR	Removed 20 ns and 35 ns speed bin from Product offering Removed 24-pin (300-Mil) Molded DIP package Changed the description of $I_{IX}$ from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed $I_{OS}$ parameter from DC Electrical Characteristics table Updated the ordering information table